

# **EPCQ-A Serial Configuration Device** Datasheet



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## **1. EPCQ-A Serial Configuration Device Datasheet**

#### **Related Information**

AN822: Intel<sup>®</sup> Configuration Device Migration Guideline

## **1.1. Supported Devices**

#### Table 1. Supported Intel EPCQ-A Devices

Device	Memory Size (bits)	On-Chip Decompression Support	ISP Support	Cascading Support	Reprogrammable	Recommended Operating Voltage (V)
EPCQ4A	4,194,304	No	Yes	No	Yes	3.3
EPCQ16A	16,777,216	No	Yes	No	Yes	3.3
EPCQ32A	33,554,432	No	Yes	No	Yes	3.3
EPCQ64A	67,108,864	No	Yes	No	Yes	3.3
EPCQ128A	134,217,728	No	Yes	No	Yes	3.3

## **1.2. Features**

EPCQ-A devices offer the following features:

- Serial or quad-serial FPGA configuration in devices that support active serial (AS) x1 or AS  $x4^{(1)}$  configuration schemes
- Low cost, low pin count, and non-volatile memory
- 2.7-V to 3.6-V operation
- Available in 8-pin small-outline integrated circuit (SOIC) package for EPCQ4A, EPCQ16A, and EPCQ32A devices
- Available in 16-pin SOIC package for EPCQ64A and EPCQ128A devices
- Reprogrammable memory more than 100,000 program-erase cycles
- Write protection support for memory sectors using status register bits
- Fast read, extended dual input fast read, and extended quad input fast read of the entire memory using a single operation code
- Reprogrammable with an external microprocessor using the SRunner software driver
- In-system programming (ISP) support with the SRunner software driver



<sup>&</sup>lt;sup>(1)</sup> AS x4 is not applicable for EPCQ4A.

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- ISP support with Intel $^{\ensuremath{\mathbb{R}}}$  FPGA Download Cable II, Intel FPGA Download Cable, or Intel FPGA Ethernet Cable
- By default, the memory array is erased and the bits are set to  $\ensuremath{\mathtt{1}}$
- More than 20-year data retention
- Supports JEDEC standard Serial Flash Discoverable Parameter (SFDP)

## **1.3. Operating Conditions**

## **1.3.1. Absolute Maximum Ratings**

#### Table 2. Absolute Maximum Ratings for EPCQ-A Devices

Symbol	Parameter	Condition	Min	Max	Unit
V <sub>CC</sub>	Supply voltage	With respect to GND	-0.6	4.6	V
V <sub>IO</sub>	Input or output voltage	With respect to GND	-0.6	V <sub>CC</sub> +0.4	V
T <sub>STG</sub>	Storage temperature	No bias	-65	150	°C
V <sub>IT</sub>	Transient voltage on any pin	< 20ns transient relative to GND	-2.0	V <sub>CC</sub> +2.0	V
P <sub>D</sub>	Power dissipation	EPCQ4A	_	18	mW
		EPCQ16A, EPCQ32A, and EPCQ64A	_	54	mW
		EPCQ128A	_	72	mW
I <sub>MAX</sub>	DC V <sub>CC</sub> or GND current	EPCQ4A	_	5	mA
		EPCQ16A, EPCQ32A, and EPCQ64A	_	15	mA
		EPCQ128A	_	20	mA

## **1.3.2. Recommended Operating Conditions**

#### Table 3. Recommended Operating Conditions for EPCQ-A Devices

	Symbol	Parameter	Condition	Min	Мах	Unit
\ \	V <sub>CC</sub>	Supply voltage	(2)	2.7	3.6	V
	T <sub>A</sub>	Ambient temperature, Operating	For industrial use	-40	85	°C

*Note:* For the junction temperature (T<sub>J</sub>), follow the T<sub>A</sub> specification.

 $<sup>^{(2)}</sup>$  V<sub>CC</sub> voltage during a Read operation can operate across the min and max range but should not exceed  $\pm 10\%$  of the programming (erase/write) voltage.





## 1.3.3. DC Operating Conditions

#### Table 4. DC Operating Conditions for EPCQ-A Devices

Symbol	Parameter	Condition	Min	Max	Unit
V <sub>IH</sub>	High-level input voltage	-	0.7 x V <sub>CC</sub>	$V_{CC} + 0.4$	V
V <sub>IL</sub>	Low-level input voltage	-	-0.5	0.3 x V <sub>CC</sub>	V
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> - 0.2	_	V
V <sub>OL</sub>	Low-level output voltage for EPCQ4A	I <sub>OL</sub> = 100 μA	_	0.4	V
	Low-level output voltage for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A		_	0.2	V
II	Input leakage current	V <sub>I</sub> =V <sub>CC</sub> or GND	-2	2	μA
I <sub>OZ</sub>	Tri-state output off-state current	$V_0 = V_{CC}$ or GND	-2	2	μA
I <sub>LR</sub>	Input leakage	0≤/Reset <v<sub>CC</v<sub>	_	12	μA
		/Reset = V <sub>CC</sub>	_	1	μA
R <sub>PR</sub>	Pull-up resistance	_	300	1000	kΩ

## **1.3.4. AC Measurement Conditions**

#### Table 5. AC Measurement Conditions for EPCQ-A Devices

Symbol	Parameter	Min	Max	Unit
CL	Load Capacitance	—	30	pF
T <sub>R</sub> , T <sub>F</sub>	Input Rise and Fall Times	_	5	ns
V <sub>IN</sub>	Input Pulse Voltages	0.1 V <sub>CC</sub> t	V	
IN	Input Timing Reference Voltages 0.3 V <sub>CC</sub> to 0.7 V <sub>CC</sub>			
Out	Output Timing Reference Voltages	0.5 V <sub>CC</sub> t	o 0.5 V <sub>CC</sub>	V

#### Figure 1. AC Measurement I/O Waveform



## 1.3.5. ICC Supply Current

### Table 6. I<sub>CC</sub> Supply Current AC Measurement

Symbol	Parameter	Condition	Min	Max	Unit
I <sub>CC0</sub>	V <sub>CC</sub> supply current for EPCQ4A, EPCQ16A, EPCQ32A, and EPCQ64A	Standby	10	50	μA
	V <sub>CC</sub> supply current for EPCQ128A		10	60	
				сог	ntinued



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Symbol	Parameter	Condition	Min	Max	Unit
I <sub>CC1</sub>	V <sub>CC</sub> supply current for EPCQ4A	During active power mode	1	5	mA
	V <sub>CC</sub> supply current for EPCQ16A, EPCQ32A, and EPCQ64A		1	15	
	V <sub>CC</sub> supply current for EPCQ128A		1	20	

## 1.3.6. Capacitance

#### Table 7.Capacitance for EPCQ-A Devices

Capacitance is sample-tested only at  $T_A$  = 25 °C and at  $V_{CC}$  = 3.0 V.

Symbol	Parameter	Condition	Min	Max	Unit
C <sub>IN</sub>	Input pin capacitance	V <sub>IN</sub> =0 V	_	6	pF
C <sub>OUT</sub>	Output pin capacitance	V <sub>OUT</sub> =0 V	_	8	pF

## **1.4. Pin Information**

## 1.4.1. Pin-Out Diagram for EPCQ4A, EPCQ16A and EPCQ32A Devices

## Figure 2. AS x1 and AS x4 Pin-Out Diagrams for EPCQ4A, EPCQ16A, and EPCQ32A Devices

Note: EPCQ4A supports AS x1 only.





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## 1.4.2. Pin-Out Diagram for EPCQ64A and EPCQ128A Devices

#### Figure 3. AS x1 and AS x4 Pin-Out Diagrams for EPCQ64A and EPCQ128A Devices



Notes:

*N.C pins must be left unconnected.* 

There is an internal pull-up resistor for the dedicated nRESET pin. If the reset function is not needed, connect this pin to Vcc or leave it unconnected.

## 1.4.3. EPCQ-A Device Pin Description

#### Table 8. EPCQ-A Device Pin Description

Pin Number in 8-Pin SOIC PackagePin Number in 8-Pin SOIC PackagePin Number in 16-Pin SOIC PackageDATA0515515I/ODATA0515515I/ODATA0515515For AS x1 mode, use this pin at pin to write or program the EP During write or program opera latched at rising edges of the I pin is equivalent to the ASDI p pro AS x4 mode, use this pin at During write or program opera as an input pin that serially tra the EPCQ-A device. The data at edges of the DCLK signal. Duri configuration operations, this p output signal pin that serially to the EPCQ-A device to the FF shifted out at falling edges of the DCLK signal put fast read output fast read operations. this pin acts as an input pin that serially to the EPCQ-A device. The data at edges of the DCLK signal put fast read output signal pin that serially to the SDCA device. The data at edges of the DCLK signal point that serially to the EPCQ-A device. The data at edges of the DCLK signal pin that serially to this pin acts as an input pin that serially to the SDCA device. The data at edges of the DCLK signal pin that serially to the SDCA device. The shifted out at falling edges of the During the quadinput fast read operations. This pin acts as an input pin the the SDCA device. The shifted out at falling edges of the DCLK signal pin that serially to the SDCA device. The shifted out at falling edges of the DCLK signal pin that serially to the SDCA device. The shifted out fast read operations. This pin acts as an input pin the shifted out fast read operations. This pin acts as an input pin that serial pin the SDCA device. The shifted out fast read operations. This pin acts as an input pin the shifted out fast	n	Description	Pin Type	AS x1 Pin-Out AS x4 Pin-Out Diagram Diagram		Pin Name		
pin to write or program the EP During write or program opera latched at rising edges of the I pin is equivalent to the ASDI p For AS x4 mode, use this pin a During write or program opera as an input pin that serially tra the EPCQ-A device. The data a edges of the DCLK signal. Duri configuration operations, this p output signal pin that serially to of the EPCQ-A device to the FF shifted out at falling edges of t During the quad input fast writ this pin acts as an input pin th data into the EPCQ-A device. T at rising edges of the DCLK sig extended dual input fast read				Number in 16-Pin SOIC	Number in 8-Pin SOIC	Number in 16-Pin SOIC	Number in 8-Pin SOIC	
	PCQ-A device. ations, data are DCLK signal. This pin in EPCS devices as an I/O signal pin rations, this pin acts ransfers data into are latched at rising ring read or pin acts as an transfers data out FPGA. The data is the DCLK signal. rite bytes operation, hat serially transfers The data is latched ignal. During I or extended quad	pin to write or program the EP During write or program opera latched at rising edges of the I pin is equivalent to the ASDI p For AS x4 mode, use this pin a During write or program opera as an input pin that serially tra the EPCQ-A device. The data a edges of the DCLK signal. Duri configuration operations, this p output signal pin that serially fo the EPCQ-A device to the FF shifted out at falling edges of During the quad input fast wri this pin acts as an input pin th data into the EPCQ-A device. The at rising edges of the DCLK signal	I/O	15	5	15	5	DATA 0

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DataData1000000000000000000000000000000000000	Pin Name	e AS x1 Pin-Out AS x4 Pin-Out Diagram Diagram		Pin Type	Description		
DATA1Z8Z8I/OFor AS X1 and x4 modes, use this pin as an output signal pin that serially transfers data out of the EPC2.A device to the PCA. Hourd at a falling edges of the DCLX signal.DATA1Z8Z8I/OFor AS X1 and x4 modes, use this pin as an output signal pin that serially transfers data out of the EPC2.A device to the PFCA during read or configuration operations. The transition of the signal is at falling edges of the DCLX signal.DATA2SSI/OFor AS X1 and x4 modes, use this pin as an output signal pin that serially transfers data into the EPC2.A device. The data is fulling edges of the DCLX signal.DATA2SSPFor AS X1 mode, this pin as an output signal pin that serially transfer data out of the EPC2.A device to the EPCA device to the EP		Number in 8-Pin SOIC	Number in 16-Pin SOIC	Number in 8-Pin SOIC	Number in 16-Pin SOIC		
Market Barket 							of the EPCQ-A device to the FPGA. The data is
For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operation, this pin acts as an output signal pin that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operation, this pin acts as an output signal pin that serially transfers data out of the EPCQ-A device to the FPGA. The data is shifted out at falling edges of the DCLK signal.DATA371I/OFor AS x1 mode, this pin must connect to Vcc. For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA. The data is shifted out at falling edges of the DCLK signal.DATA371I/OFor AS x1 mode, this pin must connect to Vcc. For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operations. The transition of the signal is at falling edges of the DCLK signal.nCS1717InputnCS1717InputDCLK6166InputThe experiment of the signal is in signal signal is in high, the device is eabled and its in active mode. After power up, the EPCQ-A device requires a falling edge on the nCS signal before you begin any operation.	DATA1	2	8	2	8	I/O	output signal pin that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operations. The transition of the signal is at falling edges of the DCLK signal. This pin is equivalent to the DATA pin in EPCS devices. During the quad input fast write bytes operation, this pin acts as an input signal pin that serially transfers data into the EPCQ-A device. The data is latched at rising edges of the DCLK signal. During extended quad input fast read operations, this pin acts as an output signal pin that serially transfer data out of the EPCQ-A device to the FPGA. The data is shifted out at falling edges of the DCLK signal. During read, configuration, or program operations, you can enable the EPCQ-A
For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operations. The transition of the signal is at falling edges of the DCLK signal. During the extended quad input fast read operation, this pin acts as an output signal pin that serially transfers data out of the EPCQ-A device to the FPGA. The data is shifted out at falling edges of the DCLK signal.nCS1717InputnCS1717InputDCLK616616InputThe active low nCS input signal toggles at the beginning and end of a valid operation. When this signal is high, the device is deselected and the DATA[3:0] pins are tri-stated. When this signal is low, the device is enabled and is in active mode. After power up, the EPCQ-A device requires a falling edge on the nCS signal before you begin any operation.DCLK616616Input	DATA2	_	_	3	9	I/O	For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operations. The transition of the signal is at falling edges of the DCLK signal. During the extended quad input fast read operation, this pin acts as an output signal pin that serially transfers data out of the EPCQ-A device to the FPGA. The data is shifted out at
DCLK616616InputThe FPGA provides the DCLK signal. This signal	DATA3	_	_	7	1	I/O	For AS x4 mode, use this pin as an output signal that serially transfers data out of the EPCQ-A device to the FPGA during read or configuration operations. The transition of the signal is at falling edges of the DCLK signal. During the extended quad input fast read operation, this pin acts as an output signal pin that serially transfers data out of the EPCQ-A device to the FPGA. The data is shifted out at
provides the timing for the serial interface. The	nCS	1	7	1	7	Input	beginning and end of a valid operation. When this signal is high, the device is deselected and the DATA[3:0] pins are tri-stated. When this signal is low, the device is enabled and is in active mode. After power up, the EPCQ-A device requires a falling edge on the nCS signal before
	DCLK	6	16	6	16	Input	provides the timing for the serial interface. The



Pin Name		AS x1 Pin-Out Diagram		AS x4 Pin-Out Diagram		Description
	Pin Number in 8-Pin SOIC Package	Pin Number in 16-Pin SOIC Package	Pin Number in 8-Pin SOIC Package	Pin Number in 16-Pin SOIC Package		
						latched to the EPCQ-A device at rising edges of the DCLK signal. The data on the DATA[3:0] pins change after the falling edge of the DCLK signal and are latched in to the FPGA on the next falling edge of the DCLK signal.
nRESET	_	3	_	3	Input	Dedicated hardware reset pin. When it's driven low for a minimum period of ~1 $\mu$ S, the EPCQ-A device will terminate any external or internal operations and return to its power-on state. There is an internal pull-up resistor for the dedicated nRESET pin on the SOIC-16 package. If the reset function is not needed, you can connect it to V <sub>CC</sub> or leave it unconnected.
V <sub>CC</sub>	8	2	8	2	Power	Connect the power pins to a 3.3-V power supply.
GND	4	10	4	10	Ground	Ground pin.

## **1.5. Device Package and Ordering Code**

## 1.5.1. Package

The EPCQ4A, EPCQ16A, and EPCQ32A devices are available in 8-pin SOIC packages. The EPCQ64A and EPCQ128A devices are available in 16-pin SOIC packages.

## **1.5.2. Ordering Code**

#### Table 9. EPCQ-A Device Ordering Codes

Device	Ordering Code <sup>(3)</sup>
EPCQ4A	EPCQ4ASI8N
EPCQ16A	EPCQ16ASI8N
EPCQ32A	EPCQ32ASI8N
EPCQ64A	EPCQ64ASI16N
EPCQ128A	EPCQ128ASI16N



 $<sup>^{(3)}\,</sup>$  N indicates that the device is lead free.



## **1.6. Memory Array Organization**

#### Table 10. Supported Memory Array Organization in EPCQ-A Devices

Details	EPCQ4A	EPCQ16A	EPCQ32A	EPCQ64A	EPCQ128A	
Bytes	524,288 bytes [4 megabits (Mb)]	2,097,152 bytes [16 Mb]	4,194,304 bytes (32 Mb)	8,388,608 bytes (64 Mb)	16,777,216 bytes (128 Mb)	
Number of sectors	8	32	64	128	256	
Bytes per sector	65,536 bytes [512 kilobits (Kb)]					
Total numbers of subsectors <sup>(4)</sup>	128	512	1,024	2,048	4,096	
Bytes per subsector		4	,096 bytes (32 Kb	)	•	
Pages per sector			256			
Total number of pages	2,048	8,192	16,384	32,768	65,536	
Bytes per page	256 bytes					

## 1.6.1. Address Range for EPCQ4A

#### Table 11. Address Range for Sectors 7..0 and Subsectors 127..0 in EPCQ4A Devices

Sector	Subsector	Address Range (Byte	Addresses in HEX)
		Start	End
7	127	7F000	7FFFF
	126	7E000	7EFFF
	114	72000	72FFF
	113	71000	71FFF
	112	70000	70FFF
6	111	6F000	6FFFF
	110	6E000	6EFFF
	98	62000	62FFF
	97	61000	61FFF
	96	60000	60FFF
1	31	1F000	1FFFF
	30	1E000	1EFFF
			continued

<sup>&</sup>lt;sup>(4)</sup> Every sector is further divided into 16 subsectors with 4 KB of memory. Therefore, there are 128 (8 x 16) subsectors for the EPCQ4A device, 512 (32 x 16) subsectors for the EPCQ16A device, 1,024 (64 x 16) subsectors for the EPCQ32A device, 2,048 (128 x 16) subsectors for the EPCQ64A device, and 4,096 (256 x 16) subsectors for the EPCQ128A device.



Sector	Subsector	Address Range (Byte Addresses in HEX)		
		Start	End	
	18	12000	12FFF	
	17	11000	11FFF	
	16	10000	10FFF	
0	15	F000	FFFF	
	14	E000	EFFF	
	2	2000	2FFF	
	1	1000	1FFF	
	0	H'000000	H'0000FFF	

## 1.6.2. Address Range for EPCQ16A

### Table 12. Address Range for Sectors 31..0 and Subsectors 511..0 in EPCQ16A Devices

Sector	Subsector	Address Range (Byte	e Addresses in HEX)
		Start	End
31	511	1FF000	1FFFFF
	510	1FE000	1FEFFF
	498	1F2000	1F2FFF
	497	1F1000	1F1FFF
	496	1F0000	1F0FFF
30	495	1EF000	1EFFFF
	494	1EE000	1EEFFF
	482	1E2000	1E2FFF
	481	1E1000	1E1FFF
	480	1E0000	1E0FFF
1	31	1F000	1FFFF
	30	1E000	1EFFF
	18	12000	12FFF
	17	11000	11FFF
	16	10000	10FFF
0	15	F000	FFFF
	14	E000	EFFF
			continued





Sector	Subsector	Address Range (Byte Addresses in HEX)	
		Start	End
	2	2000	2FFF
	1	1000	1FFF
	0	H'000000	H'0000FFF

## 1.6.3. Address Range for EPCQ32A

## Table 13. Address Range for Sectors 63..0 and Subsectors 1023..0 in EPCQ32A Devices

Sector	Subsector	Address Range (Byte	e Addresses in HEX)
		Start	End
63	1023	3FF000	3FFFFF
	1022	3FE000	3FEFFF
	1010	3F2000	3F2FFF
	1009	3F1000	3F1FFF
	1008	3F0000	3F0FFF
62	1007	3EF000	3EFFFF
	1006	3EE000	3EEFFF
	994	3E2000	3E2FFF
	993	3E1000	3E1FFF
	992	3E0000	3E0FFF
1	31	1F000	1FFFF
	30	1E000	1EFFF
	18	12000	12FFF
	17	11000	11FFF
	16	10000	10FFF
0	15	F000	FFFF
	14	E000	EFFF
	2	2000	2FFF
	1	1000	1FFF
	0	H'0000000	H'0000FFF





## 1.6.4. Address Range for EPCQ64A

# Table 14.Address Range for Sectors 127..0 and Subsectors 2047..0 in EPCQ64A<br/>Devices

Sector	Subsector	Address Range (Byt	e Addresses in HEX)
		Start	End
127	2047	7FF000	7fffff
	2046	7fe000	7fefff
	2034	7F2000	7F2FFF
	2033	7F1000	7F1FFF
	2032	7F0000	7F0FFF
64	1039	40F000	40FFFF
	1038	40E000	40EFFF
	1026	402000	402FFF
	1025	401000	401FFF
	1024	400000	400FFF
63	1023	3FF000	3fffff
	1022	3FE000	3fefff
	1010	3F2000	3F2FFF
	1009	3F1000	3F1FFF
	1008	3F0000	3F0FFF
62	1007	3EF000	3effff
	1006	3EE000	3eefff
	994	3E2000	3E2FFF
	993	3E1000	3E1FFF
	992	3E0000	3E0FFF
1	31	1F000	1FFFF
	30	1E000	1efff
	18	12000	12FFF
	17	11000	11FFF
	16	10000	10FFF
0	15	F000	FFFF
	L		continued





Sector	Subsector	Address Range (Byte Addresses in HEX)		
		Start	End	
	14	E000	EFFF	
	2	2000	2FFF	
	1	1000	lfff	
	0	Н'000000	H'0000FFF	

## 1.6.5. Address Range for EPCQ128A

## Table 15.Address Range for Sectors 255..0 and Subsectors 4095..0 in EPCQ128A<br/>Devices

Sector	Subsector	Address Range (Byt	Address Range (Byte Addresses in HEX)		
		Start	End		
255	4095	FFF000	FFFFFF		
	4094	FFE000	FFEFFF		
	4082	FF2000	FF2FFF		
	4081	FF1000	FF1FFF		
	4080	FF0000	FFOFFF		
254	4079	FEF000	FEFFFF		
	4078	FEE000	FEEFFF		
	4066	FE2000	FE2FFF		
	4065	FE1000	FE1FFF		
	4064	FE0000	FEOFFF		
129	2079	81F000	81FFFF		
	2078	81E000	81EFFF		
	2066	812000	812FFF		
	2065	811000	811FFF		
	2064	810000	810FFF		
128	2063	80F000	80FFFF		
	2062	80E000	80EFFF		
	2050	802000	802FFF		
	2049	801000	801FFF		







Sector	Subsector	Address Range (Byte Addresses in HEX)		
		Start	End	
	2048	800000	800FFF	
127	2047	7 <b>FF</b> 000	7FFFFF	
	2046	7fe000	7feff	
	2034	7F2000	7F2FFF	
	2033	7F1000	7F1FFF	
	2032	7F0000	7F0FFF	
64	1039	40F000	40FFFF	
	1038	40E000	40EFFF	
	1026	402000	402FFF	
	1025	401000	401FFF	
	1024	400000	400FFF	
63	1023	3FF000	3fffff	
	1022	3FE000	3FEFFF	
	1010	3F2000	3F2FFF	
	1009	3F1000	3F1FFF	
	1008	3F0000	3F0FFF	
62	1007	3EF000	3effff	
	1006	3EE000	3eefff	
	994	3E2000	3E2FFF	
	993	3E1000	3E1FFF	
	992	3E0000	3E0FFF	
1	31	1F000	1FFFF	
	30	1E000	lefff	
	18	12000	12FFF	
	17	11000	11FFF	
	16	10000	10FFF	
0	15	F000	FFFF	
	14	E000	EFFF	
		•		



Sector	Subsector	Address Range (Byte Addresses in HEX)		
		Start	End	
	2	2000	2FFF	
	1	1000	lfff	
	0	н'000000	H'0000FFF	

## **1.7. Memory Operations**

This section describes the operations that you can use to access the memory in EPCQ-A devices. When performing the operation, addresses and data are shifted in and out of the device serially, with the MSB first.

## **1.7.1. Timing Requirements**

When the active low chip select (nCS) signal is driven low, shift in the operation code into the EPCQ-A device using theDATA0 pin. Each operation code bit is latched into the EPCQ-A device at rising edges of the DCLK signal.

While executing an operation, shift in the desired operation code, followed by the address or data bytes. See related information for more information about the address and data bytes. The device must drive the nCS pin high after the last bit of the operation sequence is shifted in.

For read operations, the data read is shifted out on the DATA[3:0] pins. You can drive the nCS pin high when any bit of the data is shifted out.

For write and erase operations, drive the nCS pin high at a byte boundary, that is in a multiple of eight clock pulses. Otherwise, the operation is rejected and not executed.

All attempts to access the memory contents while a write or erase cycle is in progress are rejected, and the write or erase cycle continues unaffected.

## **1.8. Status Register**

Table 16.	Status	Register	Bits
-----------	--------	----------	------

Bit	R/W	Default Value	Name	Value	Description			
7	R/W	0 <sup>(5)</sup>		Reserved				
6	R/W	0 <sup>(5)</sup>	Reserved					
5	R/W	0	TB (Top/Bottom Bit)	<ul> <li>1=Protected area starts from the bottom of the memory array.</li> <li>0=Protected area starts from the top of the memory array.</li> </ul>	Determine that the protected area starts from the top or bottom of the memory array.			
	continued							

<sup>&</sup>lt;sup>(5)</sup> Do not program these bits to 1.





Bit	R/W	Default Value	Name	Value	Description
4	R/W	0	BP2 <sup>(6)</sup>	Table 17 on page 18 through Table 21 on page	Determine the area of
3	R/W	0	BP1 <sup>(6)</sup>	20 list the protected area with reference to the block protect bits.	the memory protected from being written or
2	R/W	0	BP0 <sup>(6)</sup>		erased unintentionally.
1	R	0	WEL (Write Enable Latch Bit)	<ul> <li>1=Allows the following operation to run:         <ul> <li>Write Bytes</li> <li>Write Status Register</li> <li>Erase Bulk</li> <li>Erase Sector</li> </ul> </li> <li>0=Rejects the above mentioned operations.</li> </ul>	Allows or rejects certain operation to run.
0	R	0	WIP (Write in Progress Bit)	<ul> <li>1=One of the following operation is in progress:</li> <li>Write Status Register</li> <li>Write Bytes</li> <li>Erase</li> <li>0=no write or erase cycle in progress</li> </ul>	Indicates if there is a command in progress.

## 1.8.1. Read Status Operation

The status register can be read continuously and at anytime, including during a write or erase operations.

#### Figure 4. Read Status Operation Timing Diagram



#### Table 17. Block Protection Bits in EPCQ4A

Status Register Content			t	Memory Content	
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area
х	0	0	0	None	All sectors
0	0	0	1	Sector 7	Sectors (0 to 6)
0	0	1	0	Sectors (6 to 7)	Sectors (0 to 5)
0	0	1	1	Sectors (4 to 7)	Sectors (0 to 3)
1	0	0	1	Sector 0	Sectors (1 to 7)
				•	continued.

<sup>(6)</sup> The erase bulk and erase die operation is only available when all the block protect bits are set to 0. When any of the block protect bits are set to 1, the relevant area is protected from being written by a write bytes operation or erased by an erase sector operation.



Status Register Content			t	Memory Content		
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area	
1	0	1	0	Sectors (0 to 1)	Sectors (2 to 7)	
1	0	1	1	Sectors (0 to 3)	Sectors (4 to 7)	
х	1	x	x	All sectors	None	

#### Table 18. Block Protection Bits in EPCQ16A

	Status Regi	ster Content		Memory	Content
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area
0	0	0	0	None	All sectors
0	0	0	1	Sector 31	Sectors (0 to 30)
0	0	1	0	Sectors (30 to 31)	Sectors (0 to 29)
0	0	1	1	Sectors (28 to 31)	Sectors (0 to 27)
0	1	0	0	Sectors (24 to 31)	Sectors (0 to 23)
0	1	0	1	Sectors (16 to 31)	Sectors (0 to 15)
0	1	1	0	All sectors	None
0	1	1	1	All sectors	None
1	0	0	0	None	All sectors
1	0	0	1	Sector 0	Sectors (1 to 31)
1	0	1	0	Sectors (0 to 1)	Sectors (2 to 31)
1	0	1	1	Sectors (0 to 3)	Sectors (4 to 31)
1	1	0	0	Sectors (0 to 7)	Sectors (8 to 31)
1	1	0	1	Sectors (0 to 15)	Sectors (16 to 31)
1	1	1	0	All sectors	None
1	1	1	1	All sectors	None

#### Table 19. Block Protection Bits in EPCQ32A

	Status Regis	ster Content		Memory Content	
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area
0	0	0	0	None	All sectors
0	0	0	1	Sector 63	Sectors (0 to 62)
0	0	1	0	Sectors (62 to 63)	Sectors (0 to 61)
0	0	1	1	Sectors (60 to 63)	Sectors (0 to 59)
0	1	0	0	Sectors (56 to 63)	Sectors (0 to 55)
0	1	0	1	Sectors (48 to 63)	Sectors (0 to 47)
0	1	1	0	Sectors (32 to 63)	Sectors (0 to 31)
0	1	1	1	All sectors	None
1	0	0	0	None	All sectors
					continue



	Status Regis	ster Content		Memory Content		
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area	
1	0	0	1	Sector 0	Sectors (1 to 63)	
1	0	1	0	Sectors (0 to 1)	Sectors (2 to 63)	
1	0	1	1	Sectors (0 to 3)	Sectors (4 to 63)	
1	1	0	0	Sectors (0 to 7)	Sectors (8 to 63)	
1	1	0	1	Sectors (0 to 15)	Sectors (16 to 63)	
1	1	1	0	Sectors (0 to 31)	Sectors (32 to 63)	
1	1	1	1	All sectors	None	

## Table 20. Block Protection Bits in EPCQ64A

Status Register Content			t	Memory Content		
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area	
0	0	0	0	None	All sectors	
0	0	0	1	Sectors (126 to 127)	Sectors (0 to 125)	
0	0	1	0	Sectors (124 to 127)	Sectors (0 to 123)	
0	0	1	1	Sectors (120 to 127)	Sectors (0 to 119)	
0	1	0	0	Sectors (112 to 127)	Sectors (0 to 111)	
0	1	0	1	Sectors (96 to 127)	Sectors (0 to 95)	
0	1	1	0	Sectors (64 to 127)	Sectors (0 to 63)	
0	1	1	1	All sectors	None	
1	0	0	0	None	All sectors	
1	0	0	1	Sectors (0 to 1)	Sectors (2 to 127)	
1	0	1	0	Sectors (0 to 3)	Sectors (4 to 127)	
1	0	1	1	Sectors (0 to 7)	Sectors (8 to 127)	
1	1	0	0	Sectors (0 to 15)	Sectors (16 to 127)	
1	1	0	1	Sectors (0 to 31)	Sectors (32 to 127)	
1	1	1	0	Sectors (0 to 63)	Sectors (64 to 127)	
1	1	1	1	All sectors	None	

### Table 21. Block Protection Bits in EPCQ128A

Status Register Content			t	Memory Content	
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area
0	0	0	0	None	All sectors
0	0	0	1	Sectors (252 to 255)	Sectors (0 to 251)
0	0	1	0	Sectors (248 to 255)	Sectors (0 to 247)
0	0	1	1	Sectors (240 to 255)	Sectors (0 to 239)
0	1	0	0	Sectors (224 to 255)	Sectors (0 to 223)
		1		L	continued





:	Status Register Content			Memory Content		
TB Bit	BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area	
0	1	0	1	Sectors (192 to 255)	Sectors (0 to 191)	
0	1	1	0	Sectors (128 to 255)	Sectors (0 to 127)	
0	1	1	1	All sectors	None	
1	0	0	0	None	All sectors	
1	0	0	1	Sectors (0 to 3)	Sectors (4 to 255)	
1	0	1	0	Sectors (0 to 7)	Sectors (8 to 255)	
1	0	1	1	Sectors (0 to 15)	Sectors (16 to 255)	
1	1	0	0	Sectors (0 to 31)	Sectors (32 to 255)	
1	1	0	1	Sectors (0 to 63)	Sectors (64 to 255)	
1	1	1	0	Sectors (0 to 127)	Sectors (128 to 255)	
1	1	1	1	All sectors	None	

## 1.8.2. Write Status Operation

The write status operation does not affect the write enable latch and write in progress bits. You can use the write status operation to set the status register block protection and top or bottom bits. Therefore, you can implement this operation to protect certain memory sectors. After setting the block protect bits, the protected memory sectors are treated as read-only memory. You must execute the write enable operation before the write status operation.

#### Figure 5. Write Status Operation Timing Diagram



Immediately after the nCS signal drives high, the device initiates the self-timed write status cycle. The self-timed write status cycle usually takes 10 ms for all EPCQ-A devices and is guaranteed to be less than 15 ms. For details about  $t_{WS}$ , refer to the related information below. You must account for this delay to ensure that the status register is written with the desired block protect bits. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed write status cycle is in progress. Write in progress bit is 1 during the self-timed write status cycle and 0 when it is complete.





## **1.9. Summary of Operation Codes**

Operation	Operation Code <sup>(7)</sup>	Address Bytes	Dummy Clock Cycles	Data Bytes	DCLK f <sub>MAX</sub> (MHz)
Read status	05h	0	0	1 to infinite <sup>(8)</sup>	100
Read bytes	03h	3	0	1 to infinite <sup>(8)</sup>	50
Read device identification	9Fh	0	16	1	100
Read silicon identification	ABh	0	24	1	100
Fast read	0Bh	3	8	1 to infinite <sup>(8)</sup>	100
Extended dual input fast read	BBh	3	4	1 to infinite <sup>(8)</sup>	100
Extended quad input fast read <sup>(9)</sup>	EBh	3	6	1 to infinite <sup>(8)</sup>	100
Write enable	06h	0	0	0	100
Write disable	04h	0	0	0	100
Write status	01h	0	0	1	100
Write bytes	02h	3	0	1 to 256 <sup>(10)</sup>	100
Quad input fast write bytes <sup>(9)</sup>	32h	3	0	1 to 256 <sup>(10)</sup>	100
Erase bulk	C7h	0	0	0	100
Erase sector	D8h	3	0	0	100
Erase subsector	20h	3	0	0	100
Read SFDP register <sup>(9)</sup>	5Ah	3	8	1 to 256	100

## 1.9.1. Read Bytes Operation (03h)

When you execute the read bytes operation, you first drive the nCS pin low and shift in the read bytes operation code, followed by a 3-byte address (A[23..0]). Each address bit must be latched in at rising edges of the DCLK signal. After the address is latched in, the memory contents of the specified address are shifted out serially on the DATA1 pin, beginning with the MSB. For reading Raw Programming Data File (**.rpd**), the content is shifted out serially beginning with the LSB. Each data bit is shifted out at falling edges of the DCLK signal. The maximum DCLK frequency during the read bytes operation is 50 MHz.

- <sup>(7)</sup> List MSB first and LSB last.
- <sup>(8)</sup> The status register or data is read out at least once and is continuously read out until the nCS pin is driven high.
- <sup>(9)</sup> This operation is not applicable for EPCQ4A.
- <sup>(10)</sup> A write bytes operation requires at least one data byte. If more than 256 bytes are sent to the device, only the last 256 bytes are written to the memory.







The first byte address can be at any location. The device automatically increases the address to the next higher address after shifting out each byte of data. Therefore, the device can read the whole memory with a single read bytes operation. When the device reaches the highest address, the address counter restarts at  $0 \ge 000000$ , allowing the memory contents to be read out indefinitely until the read bytes operation is terminated by driving the nCS signal high. If the read bytes operation is shifted in while a write or erase cycle is in progress, the operation is not executed and does not affect the write or erase cycle in progress.

## 1.9.2. Fast Read Operation (0Bh)

When you execute the fast read operation, you first shift in the fast read operation code, followed by a 3-byte address (A[23..0]), and 8 dummy clock cycles with each bit being latched-in at rising edges of the DCLK signal. Then, the memory contents at that address is shifted out on DATA1 with each bit being shifted out at a maximum frequency of 100 MHz at falling edges of the DCLK signal.





The first byte address can be at any location. The device automatically increases the address to the next higher address after shifting out each byte of data. Therefore, the device can read the whole memory with a single fast read operation. When the device reaches the highest address, the address counter restarts at  $0 \times 000000$ , allowing the read sequence to continue indefinitely.



You can terminate the fast read operation by driving the nCS signal high at any time during data output. If the fast read operation is shifted in while an erase, program, or write cycle is in progress, the operation is not executed and does not affect the erase, program, or write cycle in progress.

## 1.9.3. Extended Dual Input Fast Read Operation (BBh)

This operation is similar to the fast read operation except that the data and addresses are shifted in and out on the DATA0 and DATA1 pins.

#### Figure 8. **Extended Dual Input Fast Read Operation Timing Diagram**



## 1.9.4. Extended Quad Input Fast Read Operation (EBh)

This operation is similar to the extended dual input fast read operation except that the data and addresses are shifted in and out on the DATA0, DATA1, DATA2, and DATA3 pins.



#### Figure 9. **Extended Quad Input Fast Read Operation**





## **1.9.5. Read Device Identification Operation (9Fh)**

This operation reads the 8-bit device identification of the EPCQ-A device from the DATA1 output pin. If this operation is shifted in while an erase or write cycle is in progress, the operation is not executed and does not affect the erase or write cycle in progress.

#### Table 22.EPCQ-A Device Identification

EPCQ-A Device	Device ID (Binary Value)
EPCQ4A	b'0001 0011
EPCQ16A	b'0001 0101
EPCQ32A	b'0001 0110
EPCQ64A	b'0001 0111
EPCQ128A	b'0001 1000

The 8-bit device identification of the EPCQ-A device is shifted out on the DATA1 pin at falling edges of the DCLK signal.

#### Figure 10. Read Device Identification Operation Timing Diagram



## **1.9.6.** Read Silicon Identification Operation (ABh)

This operation reads the 8-bit silicon ID of the EPCQ-A device from the DATA1 output pin. If this operation is shifted in during an erase or write cycle, it is ignored and does not affect the cycle that is in progress.

*Note:* This operation is applicable to EPCQ4A, EPCQ16A and EPCQ64A devices only.

The device implements the read silicon ID operation by driving the nCS signal low and then shifting in the read silicon ID operation code, followed by three dummy bytes on the DATA0 pin. The 8-bit silicon ID of the EPCQ-A device is then shifted out on the DATA1 pin at falling edges of the DCLK signal. The device can terminate the read silicon ID operation by driving the nCS signal high after reading the silicon ID at least one time. Sending additional clock cycles on DCLK while nCS is driven low can cause the silicon ID to be shifted out repeatedly.





#### Table 23. EPCQ-A Silicon Identification

EPCQ-A Device	Silicon ID (Binary Value)
EPCQ4A	b'0001 0010
EPCQ16A	b'0001 0100
EPCQ64A	b'0001 0110

#### Figure 11. Read Silicon Identification Operation Timing Diagram



## 1.9.7. Write Enable Operation (06h)

When you enable the write enable operation, the write enable latch bit is set to 1 in the status register. You must execute this operation before the write bytes, write status, erase bulk, erase sector, and quad input fast write bytes operations.

#### Figure 12. Write Enable Operation Timing Diagram



## 1.9.8. Write Disable Operation (04h)

The write disable operation resets the write enable latch bit in the status register. To prevent the memory from being written unintentionally, the write enable latch bit is automatically reset when implementing the write disable operation, and under the following conditions:

- Power up
- Write bytes operation completion
- Write status operation completion



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- Erase bulk operation completion
- Erase sector operation completion
- Quad input fast write bytes operation completion





#### 1.9.9. Write Bytes Operation (02h)

This operation allows bytes to be written to the memory. You must execute the write enable operation before the write bytes operation. After the write bytes operation is completed, the write enable latch bit in the status register is set to 0.

When you execute the write bytes operation, you shift in the write bytes operation code, followed by a 3-byte address (A[23..0]) and at least one data byte on the DATA0 pin. If the eight LSBs (A[7..0]) are not all 0, all sent data that goes beyond the end of the current page is not written into the next page. Instead, this data is written at the start address of the same page. You must ensure the nCS signal is set low during the entire write bytes operation.

#### Figure 14. Write Bytes Operation Timing Diagram



If more than 256 data bytes are shifted into the EPCQ-A device with a write bytes operation, the previously latched data is discarded and the last 256 bytes are written to the page. However, if less than 256 data bytes are shifted into the EPCQ-A device, they are guaranteed to be written at the specified addresses and the other bytes of the same page are not affected.

The device initiates a self-timed write cycle immediately after the nCS signal is driven high. For details about the self-timed write cycle time, refer to  $t_{WB}$  in the related information below. You must account for this amount of delay before another page of memory is written. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed write cycle is in progress. The write in progress bit is set to 1 during the self-timed write cycle and 0 when it is complete.



*Note:* You must erase all the memory bytes of EPCQ-A devices before you implement the write bytes operation. You can erase all the memory bytes by executing the erase sector operation in a sector or the erase bulk operation throughout the entire memory

## **1.9.10. Quad Input Fast Write Bytes Operation (32h)**

This operation is similar to the write bytes operation except that the data are shifted in on the DATA0, DATA1, DATA2, and DATA3 pins.

#### Figure 15. Quad Input Fast Write Bytes Operation Timing Diagram



## 1.9.11. Erase Bulk Operation (C7h)

This operation sets all the memory bits to 1 or  $0 \times FF$ . Similar to the write bytes operation, you must execute the write enable operation before the erase bulk operation.

You can implement the erase bulk operation by driving the nCS signal low and then shifting in the erase bulk operation code on the DATA0 pin. The nCS signal must be driven high after the eighth bit of the erase bulk operation code has been latched in.

#### Figure 16. Erase Bulk Operation Timing Diagram



The device initiates a self-timed erase bulk cycle immediately after the nCS signal is driven high. For details about the self-timed erase bulk cycle time, refer to  $t_{\text{EB}}$  in the related information below.



You must account for this delay before accessing the memory contents. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed erase cycle is in progress. The write in progress bit is set to 1 during the self-timed erase cycle and 0 when it is complete. The write enable latch bit in the status register is reset to 0 before the erase cycle is complete.

## 1.9.12. Erase Sector Operation (D8h)

The erase sector operation allows you to erase a certain sector in the EPCQ-A device by setting all the bits inside the sector to 1 or 0xFF. This operation is useful if you want to access the unused sectors as a general purpose memory in your applications. You must execute the write enable operation before the erase sector operation.

When you execute the erase sector operation, you must first shift in the erase sector operation code, followed by the 3-byte address (A[23..0]) of the chosen sector on the DATA0 pin. The 3-byte address for the erase sector operation can be any address inside the specified sector. Drive the nCS signal high after the eighth bit of the erase sector operation code has been latched in.

#### Figure 17. Erase Sector Operation Timing Diagram



The device initiates a self-timed erase sector cycle immediately after the nCS signal is driven high. For details about the self-timed erase sector cycle time, refer to  $t_{ES}$  in the related information below. You must account for this amount of delay before another page of memory is written. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed erase cycle is in progress. The write in progress bit is set to 1 during the self-timed erase cycle and 0 when it is complete. The write enable latch bit in the status register is set to 0 before the self-timed erase cycle is complete.

#### 1.9.13. Erase Subsector Operation (20h)

The erase subsector operation allows you to erase a certain subsector in the EPCQ-A device by setting all the bits inside the subsector to 1 or  $0 \times FF$ . This operation is useful if you want to access the unused subsectors as a general purpose memory in your applications. You must execute the write enable operation before the erase subsector operation.

When you execute the erase subsector operation, you must first shift in the erase subsector operation code, followed by the 3-byte address (A[23..0]) of the chosen subsector on the DATA0 pin. The 3-byte address for the erase subsector operation can be any address inside the specified subsector. For details about the subsector address range, refer to the related information below. Drive the nCS signal high after the eighth bit of the erase subsector operation code has been latched in.





#### Figure 18. Erase Subsector Operation Timing Diagram



The device initiates a self-timed erase subsector cycle immediately after the nCS signal is driven high. For details about the self-timed erase subsector cycle time, refer to related the information below. You must account for this amount of delay before another page of memory is written. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed erase cycle is in progress. The write in progress bit is set to 1 during the self-timed erase cycle and 0 when it is complete. The write enable latch bit in the status register is set to 0 before the self-timed erase cycle is complete.

## 1.9.14. Read SFDP Register Operation (5Ah)

The 256-byte SFDP register contains information about device configurations, available operations and other features.

The Read SFDP Register operation is compatible with the JEDEC SFDP standard, JESD216A. For SFDP register values and descriptions, please refer to Appendix: SFDP Register Definitions on page 34.

#### Figure 19. Read SFDP Register Operation Timing Diagram





Initiate the Read SFDP operation by driving the nCS pin low and shifting the operations code followed by a 3-byte address into the DATA0 pin. The 3-byte address content:

- A[23..8] = 0
- A[7..0] = Defines the starting byte address for the 256-byte SFDP register

Eight dummy clock cycles are required before the SFDP register contents are shifted out on the falling edge of the  $40^{\text{th}}$  DCLK with the most significant bit (MSB) first.

#### **Related Information**

Appendix: SFDP Register Definitions on page 34

### 1.10. Power Mode

EPCQ-A devices support active and standby power modes. When the nCS signal is low, the device is enabled and is in active power mode. The FPGA is configured while the EPCQ-A device is in active power mode. When the nCS signal is high, the device is disabled but remains in active power mode until all internal cycles are completed, such as write or erase operations. The EPCQ-A device then goes into standby power mode. The I<sub>CC1</sub> and I<sub>CC0</sub> parameters list the V<sub>CC</sub> supply current when the device is in active and standby power modes.

## **1.11. Timing Information**

#### **1.11.1. Write Operation Timing**

#### Figure 20. Write Operation Timing Diagram



#### Table 24. Write Operation Parameters

Parameter	Min	Typical	Мах	Unit
Write clock frequency (from the FPGA, download cable, or embedded processor) for write enable, write disable, read status, read device identification, write bytes, erase bulk, and erase sector operations.	_	-	100	MHz
DCLK high time for EPCQ4A.	4	-	-	ns
	Write clock frequency (from the FPGA, download cable, or embedded processor) for write enable, write disable, read status, read device identification, write bytes, erase bulk, and erase sector operations.	Write clock frequency (from the FPGA, — download cable, or embedded processor) for write enable, write disable, read status, read device identification, write bytes, erase bulk, and erase sector operations.	Write clock frequency (from the FPGA, download cable, or embedded processor) for write enable, write disable, read status, read device identification, write bytes, erase bulk, and erase sector operations.       —       —	Write clock frequency (from the FPGA, download cable, or embedded processor) for write enable, write disable, read status, read device identification, write bytes, erase bulk, and erase sector operations.       -       -       100





Symbol	Parameter	Min	Typical	Мах	Unit
	DCLK high time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3.4			
t <sub>CL</sub>	DCLK low time for EPCQ4A.	4	_	-	ns
	DCLK low time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3.4			
t <sub>NCSSU</sub>	Chip select (nCS) active setup time for EPCQ4A.	5	_	-	ns
	Chip select (nCS) active setup time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3	_	-	ns
t <sub>NCSH</sub>	Chip select (nCS) not active hold time for EPCQ4A.	5	_	-	ns
	Chip select (nCS) not active hold time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3	_	-	ns
t <sub>NCSSU2</sub>	Chip select (nCS) not active setup time for EPCQ4A.	5	_	-	ns
	Chip select (nCS) not active setup time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3	_	-	ns
t <sub>NCSH2</sub>	Chip select (ncs) active hold time for EPCQ4A.	5	_	-	ns
	Chip select (nCS) active hold time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3	_	_	ns
t <sub>DSU</sub>	DATA[ ] in setup time before the rising edge on DCLK	2	_	-	ns
t <sub>DH</sub>	DATA[] hold time after the rising edge on DCLK for EPCQ4A.	5	_	-	ns
	DATA[] hold time after the rising edge on DCLK for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3			
t <sub>CSH</sub>	Chip select (nCS) high time for EPCQ4A.	100	_	-	ns
	Chip select (nCS) high time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	10 or 50 <sup>(11)</sup>			
t <sub>WB</sub> (12) (13)	Write bytes cycle time for EPCQ4A.	_	0.4	0.8	ms
	Write bytes cycle time for EPCQ16A.		0.4	3	1
	Write bytes cycle time for EPCQ32A and EPCQ128A.		0.7	3	_
	Write bytes cycle time for EPCQ64A.		0.8	3	]
tws <sup>(12)</sup>	Write status cycle time	_	10	15	ms
t <sub>EB</sub> <sup>(12)</sup>	Erase bulk cycle time for EPCQ4A	_	1	4	s
	Erase bulk cycle time for EPCQ16A		5	25	1

<sup>(11)</sup> 10 ns for read and 50 ns for write, erase or program.

- $^{(12)}\,$  The Write Operation Timing Diagram does not show these parameters.
- $^{(13)}\,$  The  $t_{WB}$  parameter is for a complete page write operation.

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Symbol	Parameter	Min	Typical	Max	Unit
	Erase bulk cycle time for EPCQ32A		10	50	
	Erase bulk cycle time for EPCQ64A		20	100	
	Erase bulk cycle time for EPCQ128A		40	200	
t <sub>ES</sub> <sup>(12)</sup>	Erase sector cycle time for EPCQ4A.	_	150	1000	ms
	Erase sector cycle time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.			2000	
t <sub>ESS</sub> <sup>(12)</sup>	Erase subsector cycle time for EPCQ4A.	_	30	300	ms
	Erase subsector cycle time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.		45	400	

## 1.11.2. Read Operation Timing

#### Figure 21. Read Operation Timing Diagram



#### Table 25. Read Operation Parameters

Symbol	Parameter	Min	Max	Unit
f <sub>RCLK</sub>	Read clock frequency (from the FPGA or embedded processor) for read bytes operations	_	50	MHz
	Fast read clock frequency (from the FPGA or embedded processor) for fast read bytes operation	_	100	MHz
t <sub>CH</sub>	DCLK high time for EPCQ4A.	4 or 6 <sup>(14)</sup>	_	ns
	DCLK high time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3.4 or 9 <sup>(15)</sup>	_	ns
t <sub>CL</sub>	DCLK low time for EPCQ4A.	4 or 6 <sup>(14)</sup>	_	ns
	DCLK low time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	3.4 or 9 <sup>(15)</sup>		ns
t <sub>ODIS</sub>	Output disable time after read	_	7	ns
t <sub>CLQV</sub>	Clock low to output valid for EPCQ4A.	_	8	ns
				continued

<sup>(15)</sup> 3.4 ns for fast read and 9 ns for read.



 $<sup>^{(14)}</sup>$  4 ns for fast read and 6 ns for read.



Symbol	Parameter	Min	Max	Unit
	Clock low to output valid for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	_	6	
t <sub>CLQX</sub>	Output hold time for EPCQ4A.	0	_	ns
	Output hold time for EPCQ16A, EPCQ32A, EPCQ64A, and EPCQ128A.	1.5	_	

## **1.12. Programming and Configuration File Support**

The Intel Quartus<sup>®</sup> Prime software provides programming support for EPCQ-A devices. When you select an EPCQ-A device, the Intel Quartus Prime software automatically generates the Programmer Object File (**.pof**) to program the device. The software allows you to select the appropriate EPCQ-A device density that most efficiently stores the configuration data for the selected FPGA.

You can program the EPCQ-A device in-system by an external microprocessor using the SRunner software driver. The SRunner software driver is developed for embedded EPCQ-A device programming that you can customize to fit in different embedded systems. The SRunner software driver reads **.rpd** files and writes to the EPCQ-A devices. The programming time is comparable to the Intel Quartus Prime software programming time. Because the FPGA reads the LSB of the **.rpd** data first during the configuration process, the LSB of **.rpd** bytes must be shifted out first during the read bytes operation and shifted in first during the write bytes operation.

Writing and reading the **.rpd** file to and from the EPCQ-A device is different from the other data and address bytes.

During the ISP of an EPCQ-A device using the Intel FPGA download cables, the cable pulls the nCONFIG signal low to reset the FPGA and overrides the 10-k $\Omega$  pull-down resistor on the nCE pin of the FPGA. The download cable then uses the interface pins depending on the selected AS mode to program the EPCQ-A device. When programming is complete, the download cable releases the interface pins of the EPCQ-A device and the nCE pin of the FPGA and pulses the nCONFIG signal to start the configuration process.

The FPGA can program the EPCQ-A device in-system using the JTAG interface with the serial flash loader (SFL). This solution allows you to indirectly program the EPCQ-A device using the same JTAG interface that is used to configure the FPGA.

#### **Related Information**

Using the Intel FPGA Serial Flash Loader IP Core with the Intel Quartus Prime Software

#### Address EPCQ16A EPCQ32A EPCQ64A EPCQ128A 00H 53h 53h 53h 53h 01H 46h 46h 46h 46h 024 44h 44h 44h 44h continued...

## **1.13. Appendix: SFDP Register Definitions**



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Address	EPCQ16A	EPCQ32A	EPCQ64A	EPCQ128A
03н	50h	50h	50h	50h
04H	05h	05h	05h	05h
05H	01h	01h	01h	01h
06н	00h	00h	00h	00h
07H	FFh	FFh	FFh	FFh
08H	00h	00h	00h	00h
09н	05h	05h	05h	05h
0AH	01h	01h	01h	01h
ОВН	10h	10h	10h	10h
0CH	80h	80h	80h	80h
0 DH	00h	00h	00h	00h
0 EH	00h	00h	00h	00h
0FH	FFh	FFh	FFh	FFh
10H 7FH	FFh	FFh	FFh	FFh
80H	E5h	E5h	E5h	E5h
81H	20н	20н	20н	20h
82H	F9h	F9h	F9h	F9h
83H	FFh	FFh	FFh	FFh
84H	FFh	FFh	FFh	FFh
85H	FFh	FFh	FFh	FFh
86H	FFh	FFh	FFh	FFh
87H	00h	01h	03h	07h
88H	44h	44h	44h	44h
89н	EBh	EBh	EBh	EBh
8AH	08H	08H	08H	08H
8BH	6Bh	6Bh	6Bh	6Bh
8CH	08h	08h	08h	08h
8DH	3Bh	3Bh	3Bh	3Bh
8EH	42h	42h	42h	42h
8FH	BBh	BBh	BBh	BBh
90H	FEh	FEh	FEh	FEh
91H	FFh	FFh	FFh	FFh
92н	FFh	FFh	FFh	FFh
93н	FFh	FFh	FFh	FFh
	•			continued





Address	EPCQ16A	EPCQ32A	EPCQ64A	EPCQ128A
94н	FFh	FFh	FFh	FFh
95н	FFh	FFh	FFh	FFh
96н	00h	00h	00h	00h
97н	00h	00h	00h	00h
98H	FFh	FFh	FFh	FFh
99н	FFh	FFh	FFh	FFh
9АН	40h	40h	40h	40h
9ВН	EBh	EBh	EBh	EBh
9CH	0Ch	0Ch	0Ch	0Ch
9DH	20h	20h	20h	20h
9EH	0Fh	0Fh	0Fh	0Fh
9FH	52h	52h	52h	52h
АОН	10h	10h	10h	10h
AlH	D8h	D8h	D8h	D8h
A2H	00h	00h	00h	00h
АЗН	00h	00h	00h	00h
A4H	36h	36h	36h	36h
А5н	02h	02h	02h	02h
Абн	A6h	A6h	A6h	A6h
А7н	00h	00h	00h	00h
А8Н	82h	82h	82h	82h
А9Н	EAh	EAh	EAh	EAh
ААН	14h	14h	14h	14h
ABH	B3h	C2h	C4h	C9h
ACH	E9h	E9h	E9h	E9h
ADH	63h	63h	63h	63h
AEH	76h	76h	76h	76h
AFH	33h	33h	33h	33h
вон	7Ah	7Ah	7Ah	7Ah
B1H	75h	75h	75h	75h
B2H	7Ah	7Ah	7Ah	7Ah
вЗн	75h	75h	75h	75h
B4H	F7h	F7h	F7h	F7h
в5н	A2h	A2h	A2h	A2h
	1		н	continued



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Address	EPCQ16A	EPCQ32A	EPCQ64A	EPCQ128A
вбн	D5h	D5h	D5h	D5h
B7H	5Ch	5Ch	5Ch	5Ch
в8н	19h	19h	19h	19h
в9н	F7h	F7h	F7h	F7h
BAH	4Dh	4Dh	4Dh	4Dh
BBH	FFh	FFh	FFh	FFh
BCH	E9h	E9h	E9h	E9h
BDH	30h	30h	30h	30h
BEH	F8h	F8h	F8h	F8h
BFH	80h	80h	80h	80h

#### **Related Information**

Read SFDP Register Operation (5Ah) on page 30

# **1.14. Document Revision History for the EPCQ-A Serial Configuration Device Datasheet**

Document Version	Changes
2019.10.01	<ul> <li>Added the V<sub>IT</sub>, P<sub>D</sub>, and I<sub>MAX</sub> parameters in the <i>Absolute Maximum Ratings for EPCQ-A Devices</i> table.</li> <li>Added the I<sub>LR</sub> and R<sub>PR</sub> parameters in the <i>DC Operating Conditions for EPCQ-A Devices</i> table.</li> <li>Added a note regarding the junction temperature (T<sub>J</sub>) in the <i>Recommended Operating Conditions</i> section.</li> <li>Updated the V<sub>IO</sub> parameter in the <i>Absolute Maximum Ratings for EPCQ-A Devices</i> table.</li> <li>Editorial update—changing the term dummy cycle to dummy clock cycle.</li> </ul>
2019.05.17	Updated the dummy cycles for the read device identification and read silicon identification operations in the <i>Summary of Operation Codes</i> table.
2019.03.18	Updated the note 4 in the Supported Memory Array Organization in EPCQ-A Devices table.
2019.01.09	<ul> <li>Added t<sub>NCSSU2</sub> and t<sub>NCSH2</sub> parameters in the <i>Write Operation Parameters</i> table.</li> <li>Updated the t<sub>NCSSU</sub> and t<sub>NCSH</sub> values in the <i>Write Operation Parameters</i> table.</li> <li>Updated the <i>Write Operation Timing Diagram</i>.</li> </ul>
2018.10.04	Updated the DCLK value in the Extended Dual Input Fast Read Operation Timing Diagram.
2018.04.11	<ul> <li>Updated EPCQA instances to EPCQ-A.</li> <li>Added SFDP register operation code, description, timing diagram, and register definitions.</li> <li>Added a note stating that t<sub>WB</sub> is the time for a complete page write in <i>Write Operation Parameters</i>.</li> <li>Removed a note in <i>Summary of Operation Codes</i> table stating that Read silicon identification command is not applicable to EPCQ32A and EPCQ128A.</li> </ul>
2018.03.13	• Removed I <sub>MAX</sub> and T <sub>AMB</sub> parameters from the <i>Absolute Maximum Ratings for EPCQ-A Devices</i> table.
2018.02.15	<ul> <li>Added I<sub>MAX</sub> and T<sub>AMB</sub> parameters in the <i>Absolute Maximum Ratings for EPCQ-A Devices</i> table.</li> <li>Added data retention feature information.</li> </ul>





Date	Version	Changes
December 2017	2017.12.15	<ul> <li>Updated maximum t<sub>ODIS</sub> in the <i>Read Operation</i> <i>Parameters</i> table.</li> <li>Removed t<sub>nCLK2D</sub> from <i>Read Operation Parameters</i> table.</li> </ul>
August 2017	2017.08.02	<ul> <li>Updated ordering code number.</li> <li>Added link to AN822: Configuration Device Migration Guideline.</li> <li>Updated Extended Quad Input Fast Read and Quad Input Fast Write operations timing diagram.</li> </ul>
July 2017	2017.07.28	Initial release.



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